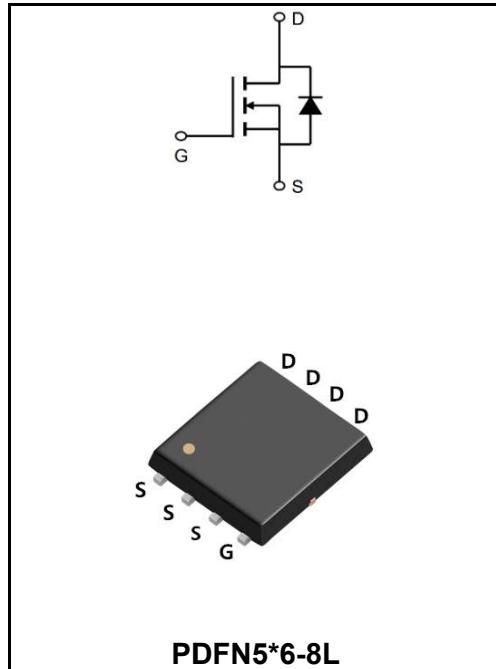


**30V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	135A
$V_{DSS}$	30V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 1.6mΩ (Type: 1.3 mΩ)


**Application**

- ◆ Lithium battery protection
- ◆ Wireless impact
- ◆ Mobile phone fast charging

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW135N03NF	PDFN5*6-8L	YFW 135N03NF XXXXX	5000PCS/Tape

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

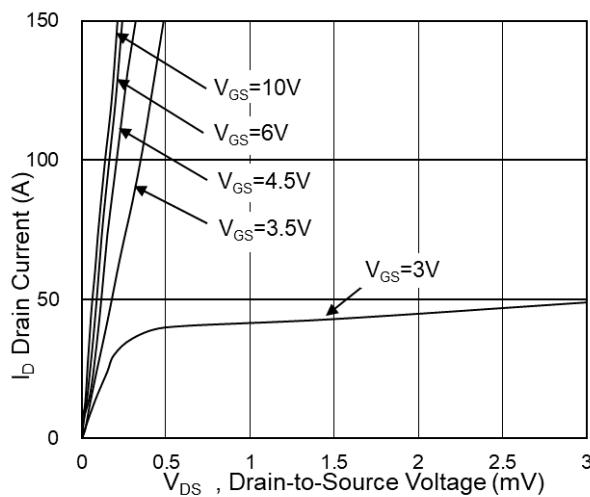
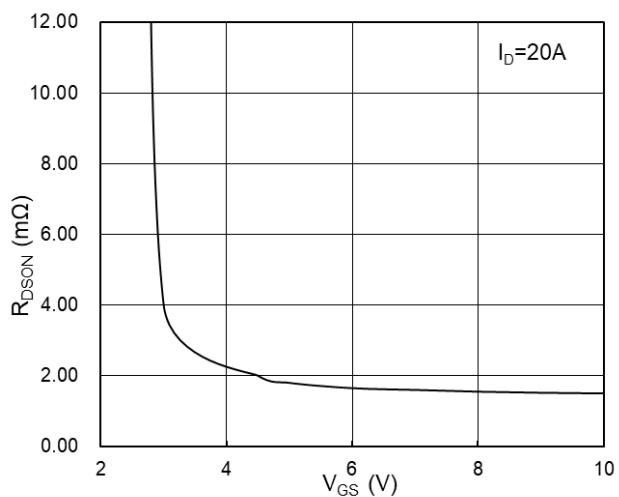
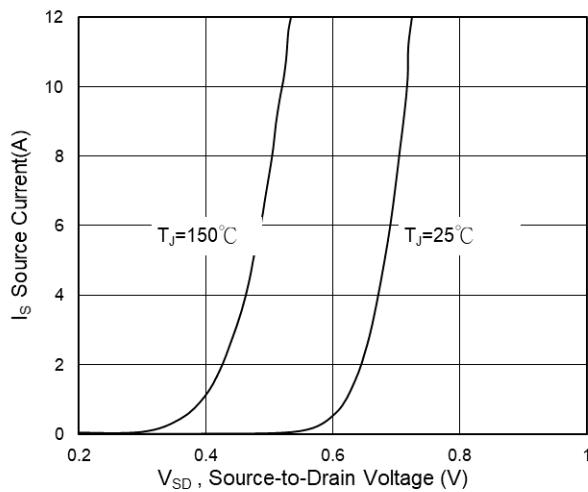
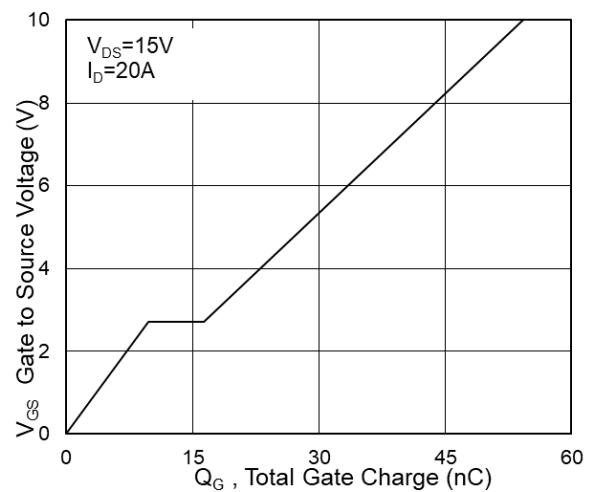
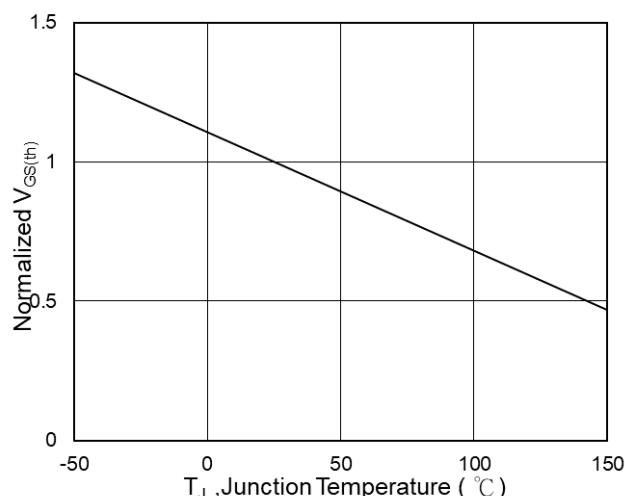
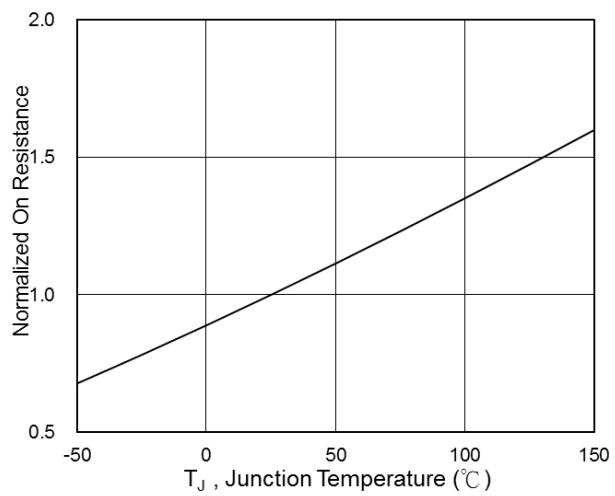
Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ 10V^{1.6}$ @ $T_c=25^\circ\text{C}$	$I_D$	135	A
Continuous Drain Current, $V_{GS} @ 10V^{1.6}$ @ $T_c=100^\circ\text{C}$	$I_D$	97	A
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_A=25^\circ\text{C}$	$I_D$	31	A
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_A=70^\circ\text{C}$	$I_D$	25	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	350	A
Single Pulsed Avalanche Energy <sup>3</sup>	$E_{AS}$	151	mJ
Avalanche Current	$I_{AS}$	55	A
Total Power Dissipation <sup>4</sup> @ $T_c=25^\circ\text{C}$	$P_D$	62.5	W
Total Power Dissipation <sup>4</sup> @ $T_A=25^\circ\text{C}$	$P_D$	2.5	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C
Thermal Resistance Junction-ambient <sup>1</sup>	$R_{\theta JA}$	50	°C/W
Thermal Resistance, Junction - Case <sup>1</sup>	$R_{\theta JC}$	2.0	°C/W

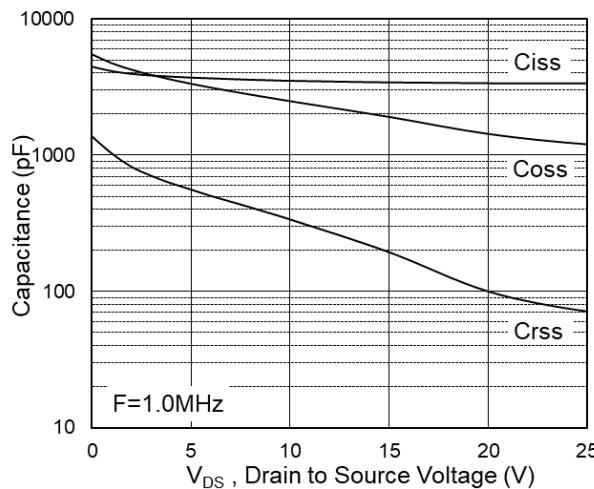
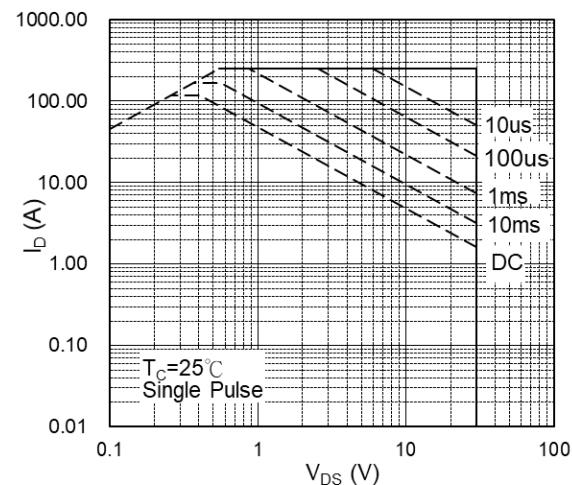
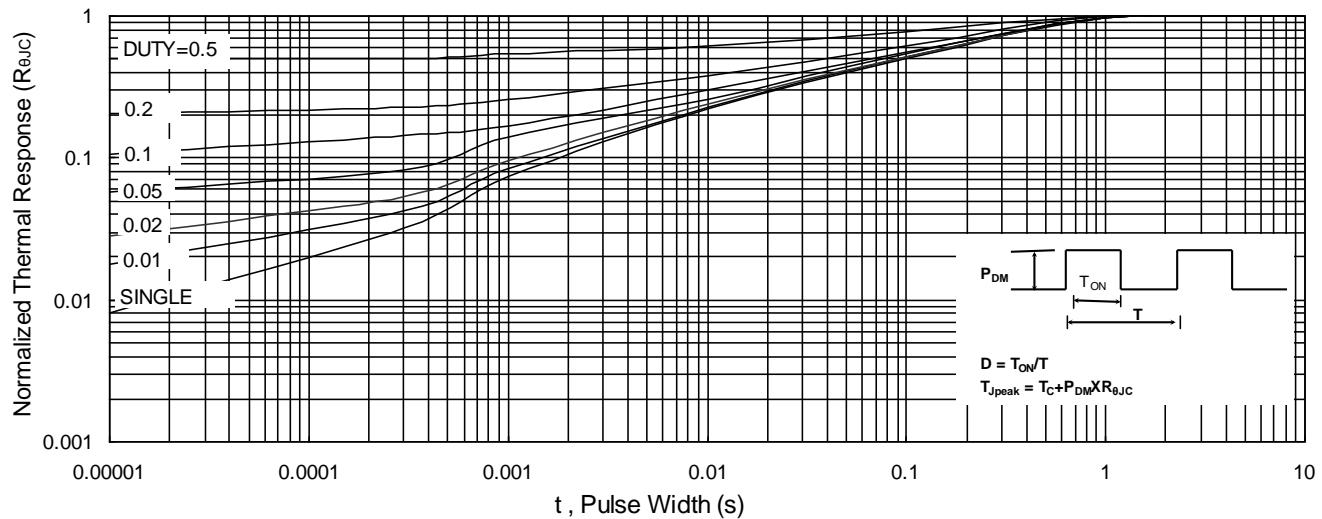
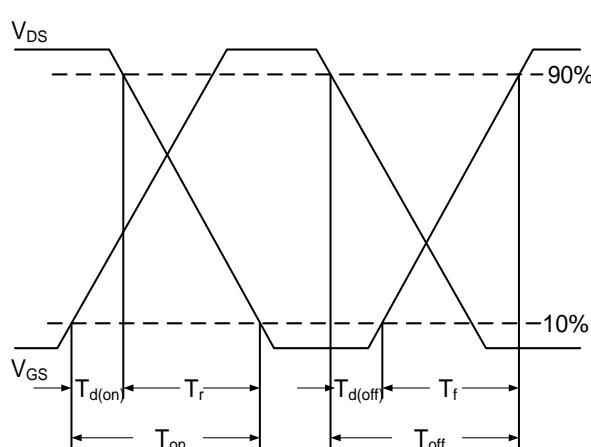
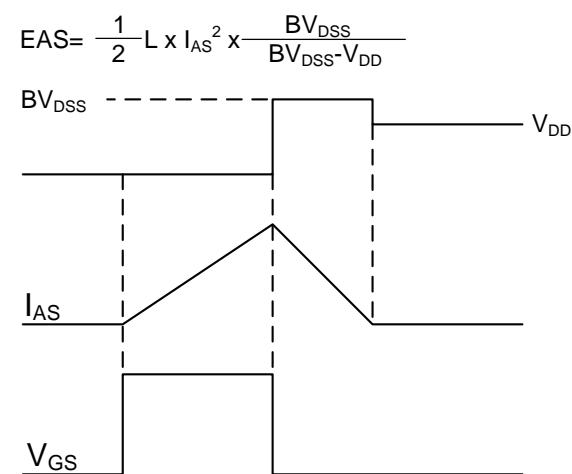
**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

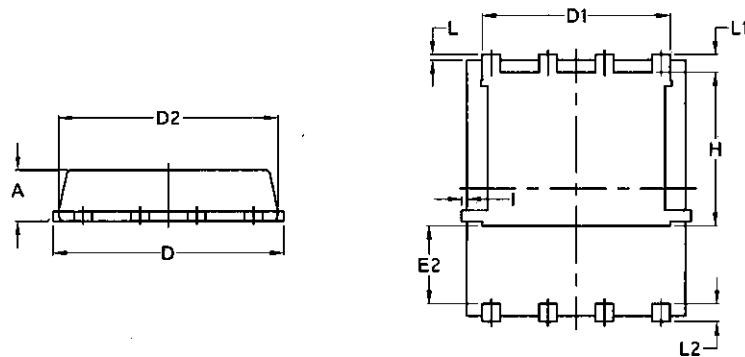
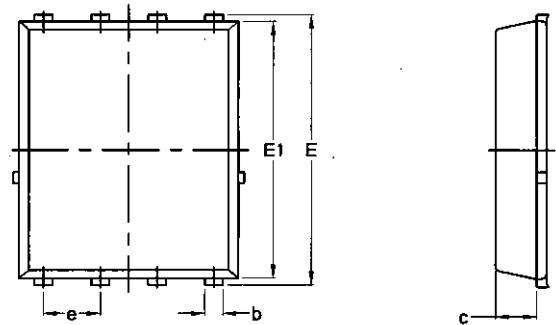
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	BV <sub>DSS</sub>	30	-	-	V
Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	R <sub>DSON</sub>	-	1.3	1.6	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A		-	1.9	2.5	
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	V <sub>GS(th)</sub>	1.2	1.6	2.2	V
Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	μA
	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		-	-	5	
Gate –Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A	g <sub>fs</sub>	-	35	-	S
Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	R <sub>g</sub>	-	1.0	-	Ω
Total Gate Charge(4.5V)	V <sub>DS</sub> =15V I <sub>D</sub> =20A V <sub>GS</sub> =10V	Q <sub>g</sub>	-	45	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	9.8	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	6.5	-	
Turn-on delay time	V <sub>DD</sub> =15V V <sub>GS</sub> =10V I <sub>D</sub> = 20A R <sub>G</sub> =3.3Ω	t <sub>d(on)</sub>	-	10.3	-	ns
Rise Time		T <sub>r</sub>	-	6.2	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	56	-	
Fall Time		t <sub>f</sub>	-	8.4	-	
Input Capacitance	V <sub>DS</sub> =15V V <sub>GS</sub> =0V f=1.0MHz	C <sub>iss</sub>	-	3420	-	pF
Output Capacitance		C <sub>oss</sub>	-	1916	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	196	-	
Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	100	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=55A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 85A.

**Ratings and Characteristic Curves**
**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.3 Source Drain Forward Characteristics**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**

**Ratings and Characteristic Curves**

**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**

**Package Outline Dimensions Millimeters**
**PDFN5\*6-8L**


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070